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PATENT NUMBER and
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U.S. UTILITY Patent Application

APPL NUM 10049875	FILING DATE 02/12/2002	CLASS 117	SUBCLASS 3	GAU 1765	EXAMINER J
**APPLICANTS: Komiya Satoshi; Yoshino Shiro; Danbata Masayoshi; Hayashida Kouichirou;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP00/05738 08/25/2000					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 11/241186 08/27/1999					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 86397	
TITLE : Silicon wafer and method for manufacture thereof, and method for evaluation of silicon wafer					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	
ISSUE FEE		Total Claims	
Amount Due	Date Paid	Print Claim for O.G.	
		DRAWING	
		Sheets Drwg.	Figs. Drwg.
		Print Fig.	
		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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